

ICE27M120W4

Silicon Carbide

Power MOSFET

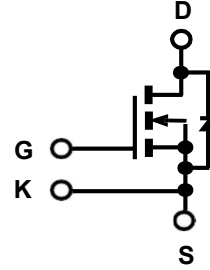
Product Summary			
I_D	$T_A=25^{\circ}\text{C}$	74.2A	Max
$V_{(BR)DSS}$	$T_C=25^{\circ}\text{C}$	1200V	Min
$r_{DS(on)}$	$V_{GS}=18\text{V}$	27m Ω	Typ
Q_g	$V_{DS}=800\text{V}$	176nC	Typ

Features

- 1200V 27mohm SiC MOSFET
- Low on-resistance
- Fast switching speed with low capacitances
- Fast intrinsic diode with low reverse recovery (Q_{RR})
- Optimized design for high performance power systems



Lead Free



TO247-4L

1: D, 2: S,
3: K, 4: G

Maximum ratings^a, at $T_j=25^{\circ}\text{C}$, unless otherwise specified

Parameter	Symbol	Conditions	Value	Unit
Continuous drain current	I_D	$T_c=25^{\circ}\text{C}$	74.2	A
		$T_c=100^{\circ}\text{C}$	52.4	
Pulsed drain current	$I_{D, \text{pulse}}$		120	A
Maximum gate source voltage	$V_{GS(max)}$		-10/+22	V
Operational gate source voltage	$V_{GS op}$		-6/+18	V
Power dissipation	P_{tot}		348.8	W
Storage temperature	T_{stg}		-55 to +175	$^{\circ}\text{C}$
Operating temperature	T_j			

^a Pulse width limited by T_{jmax}

Parameter	Symbol	Conditions	Values			Unit
			Min	Typ	Max	

Thermal characteristics

Thermal resistance, junction-case	R_{thJC}		-	-	0.43	°C/W
Thermal resistance, junction-ambient	R_{thJA}	leaded	-	-	40	
Soldering temperature, wave soldering only allowed at leads	T_{sold}	1.6mm (0.063in.) from case for 10 s	-	-	260	°C

Electrical characteristics^a, at $T_j=25^{\circ}\text{C}$, unless otherwise specified

Static characteristics

Drain-source breakdown voltage	$V_{(BR)DSS}$	$V_{GS}=0V, I_D=100\mu A$	1200	-	-	V
Gate threshold voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=11.5mA, T_j=25^{\circ}\text{C}$	2.2	3.2	4.2	
		$V_{DS}=V_{GS}, I_D=11.5mA, T_j=175^{\circ}\text{C}$	-	2.3	-	
Zero gate voltage drain current	I_{DSS}	$V_{DS}=1200V, V_{GS}=0V$	-	5	50	μA
Gate source leakage current	I_{GSS}	$V_{GS}=-10/+22V, V_{DS}=0V$	-	-	± 100	nA
Drain-source on-state resistance	$R_{DS(on)}$	$V_{GS}=18V, I_D=40A, T_j=25^{\circ}\text{C}$	-	27	38	m Ω
		$V_{GS}=18V, I_D=40A, T_j=175^{\circ}\text{C}$	-	45	-	
Gate resistance	R_G	$f=1\text{ MHz}, V_{AC}=25mV$	-	1.2	-	Ω

Dynamic characteristics

Input capacitance	C_{iss}	$V_{DS}=800V, V_{GS}=0V, f=100\text{ kHz}, V_{AC}=25mV$	-	3550	-	pF
Output capacitance	C_{oss}		-	130	-	
Reverse transfer capacitance	C_{rss}		-	10	-	
C_{OSS} stored energy	E_{oss}		-	55	-	μJ
Forward transconductance	g_{FS}	$V_{DS}=20V, I_D=40A$	-	20	-	S
Turn-on delay time	$t_{d(on)}$	$V_{DS}=800V, V_{GS}=-4/+18V, I_D=40A, R_G=10\Omega$ (External), $L=100\mu H, T_j=25^{\circ}\text{C}$	-	17	-	ns
Rise time	t_r		-	37	-	
Turn-off delay time	$t_{d(off)}$		-	56	-	
Fall time	t_f		-	20	-	
Turn-on switching energy	E_{ON}		-	850	-	μJ
Turn-off switching energy	E_{OFF}		-	370	-	

Parameter	Symbol	Conditions	Values			Unit
			Min	Typ	Max	

Dynamic characteristics

Turn-on delay time	$t_{d(on)}$	$V_{DS}=800V, V_{GS}=-4/+18V,$ $I_D=40A, R_G=10\Omega$ (External) $L=100\mu H, T_j=175^\circ C$	-	11	-	ns
Rise time	t_r		-	36	-	
Turn-off delay time	$t_{d(off)}$		-	75	-	
Fall time	t_f		-	23	-	
Turn-on switching energy	E_{ON}		-	1720	-	μJ
Turn-off switching energy	E_{OFF}		-	480	-	

Gate Charge Characteristics

Gate to source charge	Q_{gs}	$V_{DS}=800V, I_D=35A,$ $V_{GS}=-5$ to $+18V$	-	45	-	nC
Gate to drain charge	Q_{gd}		-	62	-	
Gate charge total	Q_g		-	176	-	

Reverse Diode

Continuous forward current	I_S	$V_{GS}=-4V$	-	74.2	-	A
Diode forward voltage	V_{SD}	$V_{GS}=-4V, I_{SD}=20A, T_j=25^\circ C$	-	5	-	V
		$V_{GS}=-4V, I_{SD}=20A,$ $T_j=175^\circ C$	-	4.3	-	
Reverse recovery time	t_{rr}	$V_{GS}=-4V, V_{RR}=800V,$ $I_{SD}=40A,$ $dI_F/dt=2660 A/\mu s$	-	18	-	ns
Reverse recovery charge	Q_{rr}		-	293	-	nC
Peak reverse recovery current	I_{rm}		-	27	-	A

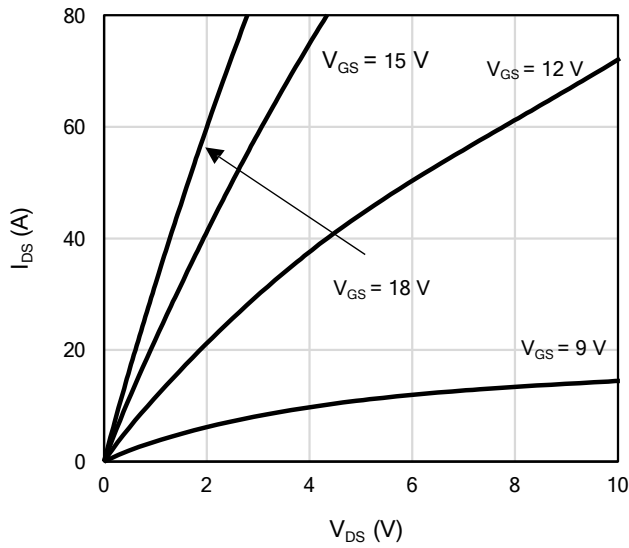


Figure 1: Output Characteristics $T_J = -40^\circ\text{C}$

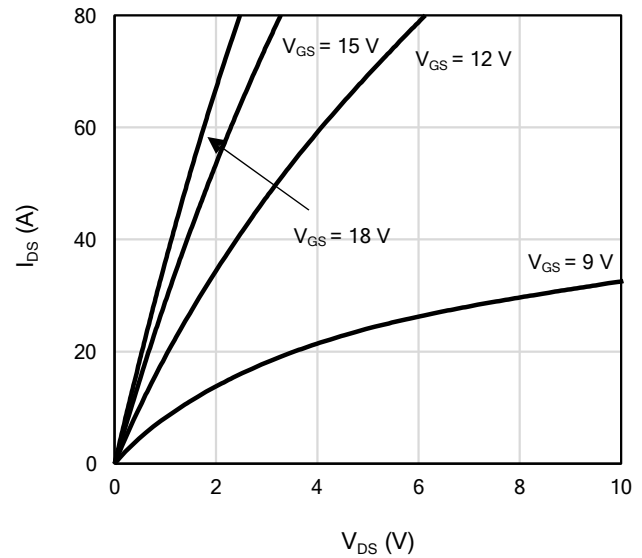


Figure 2: Output Characteristics $T_J = 25^\circ\text{C}$

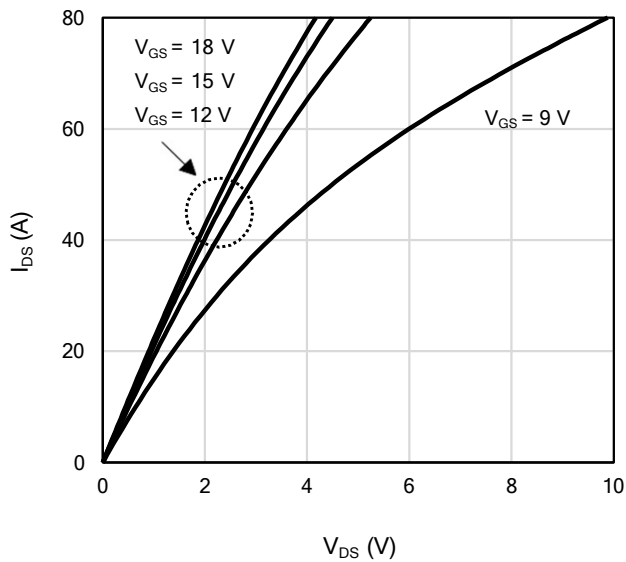


Figure 3: Output Characteristics $T_J = 175^\circ\text{C}$

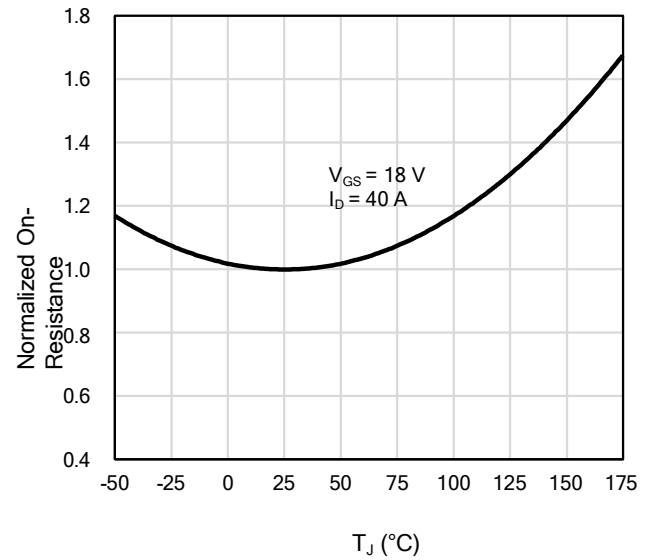


Figure 4: Normalized On-Resistance vs. Temperature

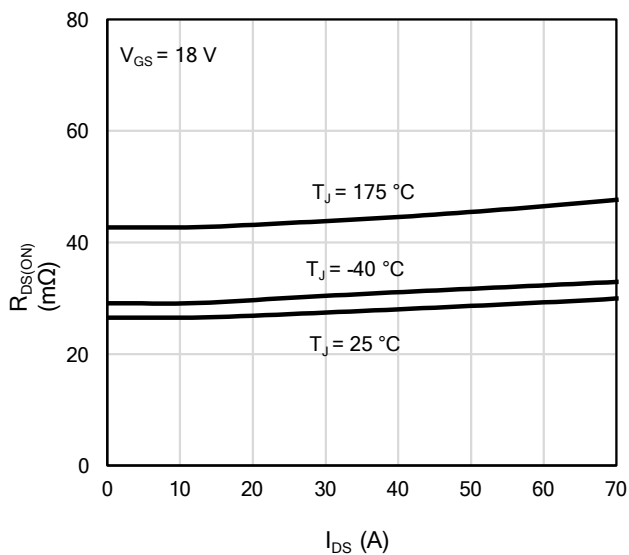


Figure 5: On-Resistance vs. Drain Current
For Various Temperatures

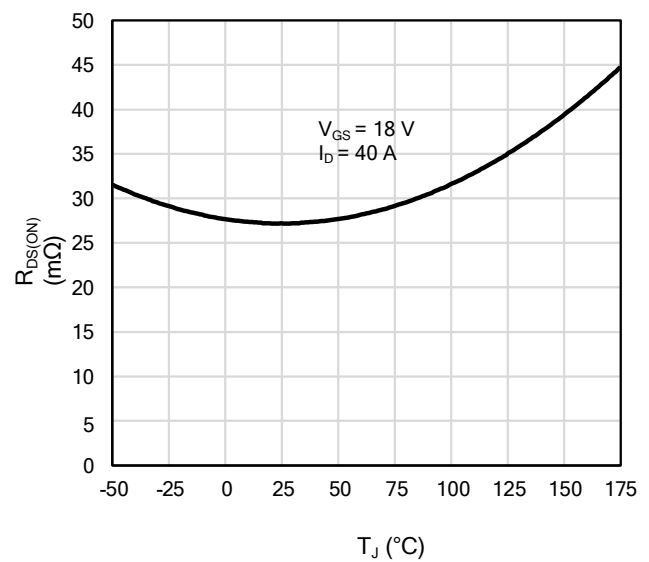


Figure 6: On-Resistance vs. Temperature

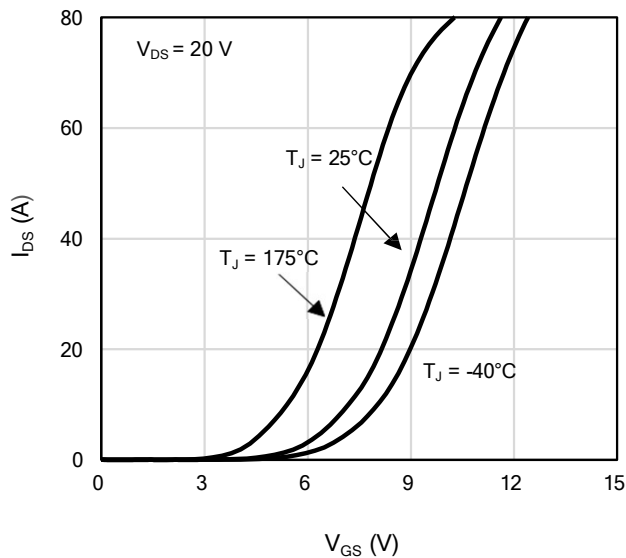


Figure 7: Transfer Characteristics For Various Junction Temperature

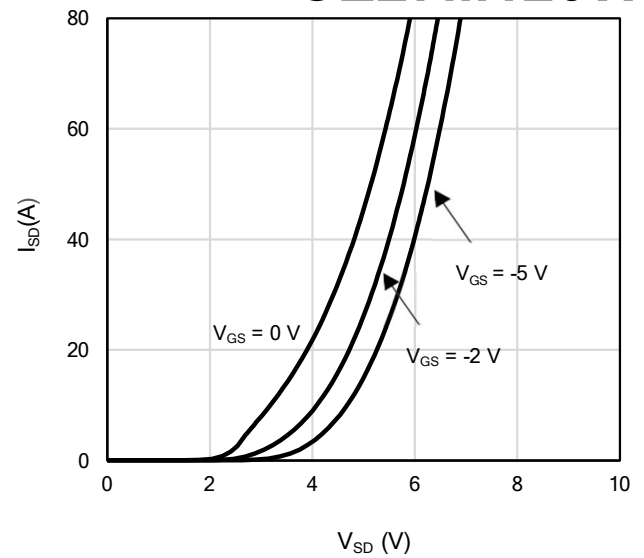


Figure 8: Body Diode Characteristics at -40°C

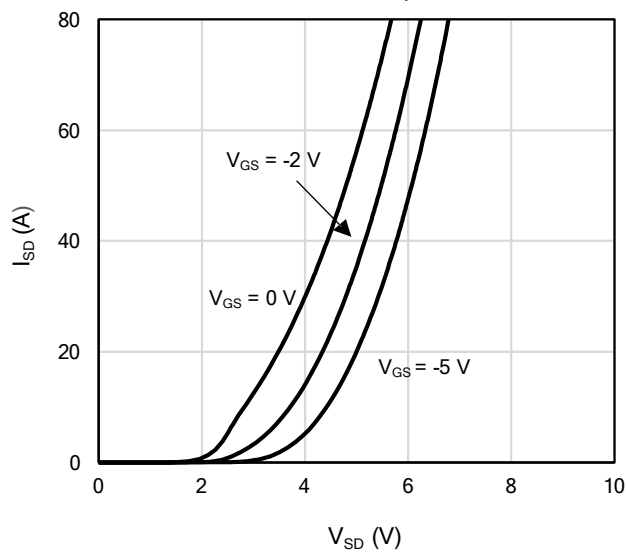


Figure 9: Body Diode Characteristics at 25°C

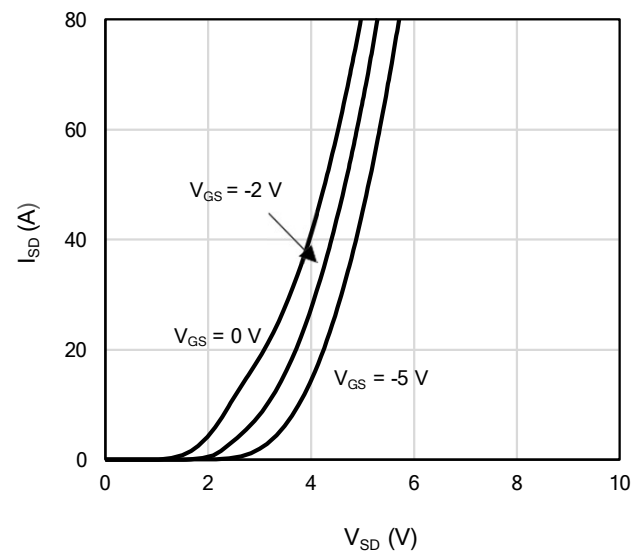


Figure 10: Body Diode Characteristics at 175°C

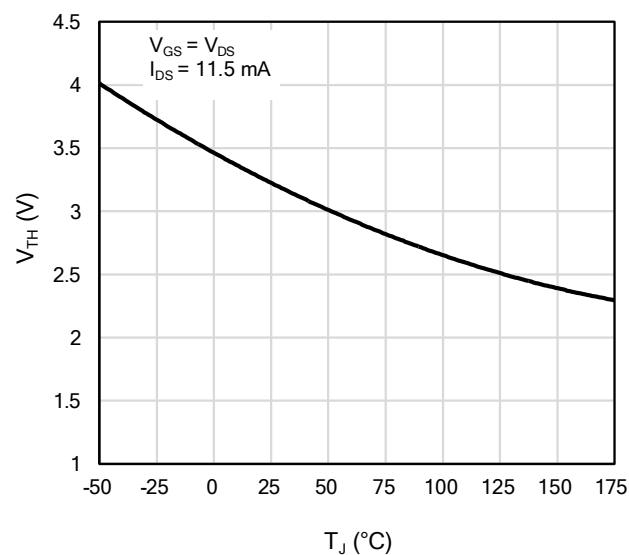


Figure 11: Threshold Voltage vs. Temperature

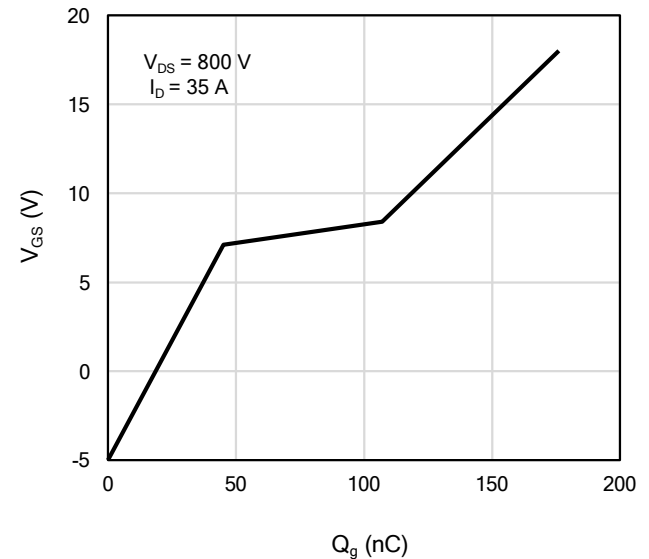


Figure 12: Gate-Charge Characteristics

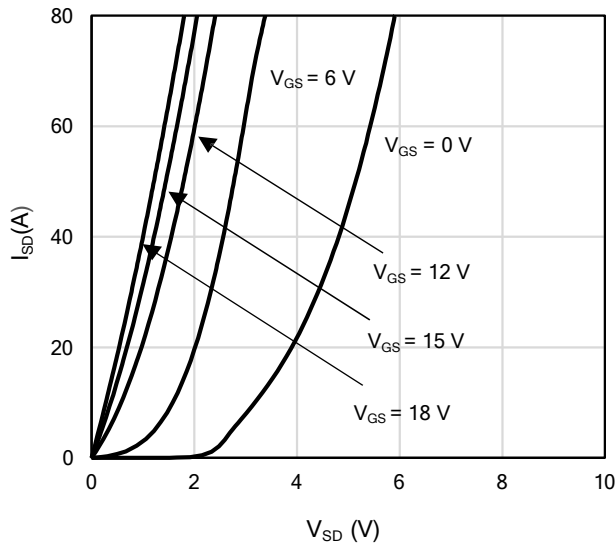


Figure 13: 3rd Quadrant Characteristics at -40°C

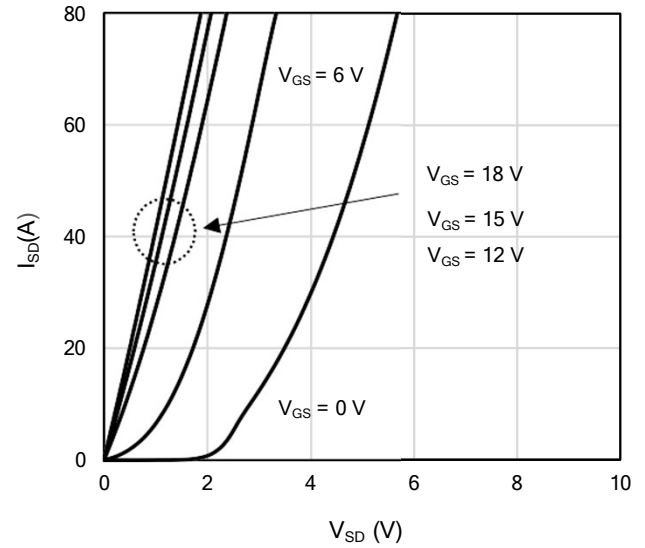


Figure 14: 3rd Quadrant Characteristics at 25°C

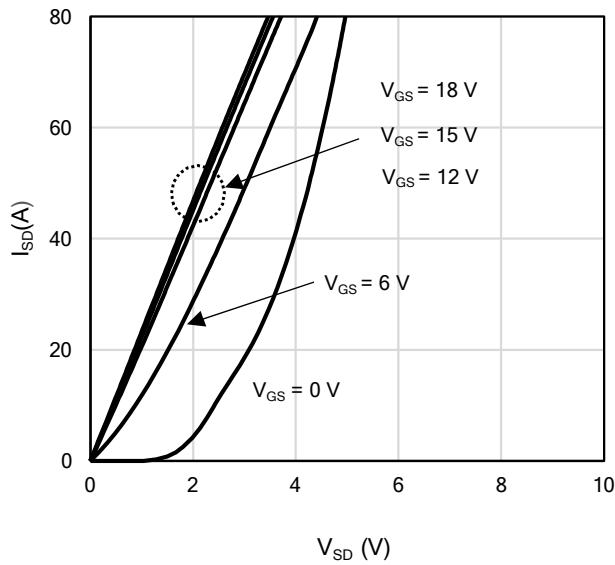


Figure 15: 3rd Quadrant Characteristics at 175°C

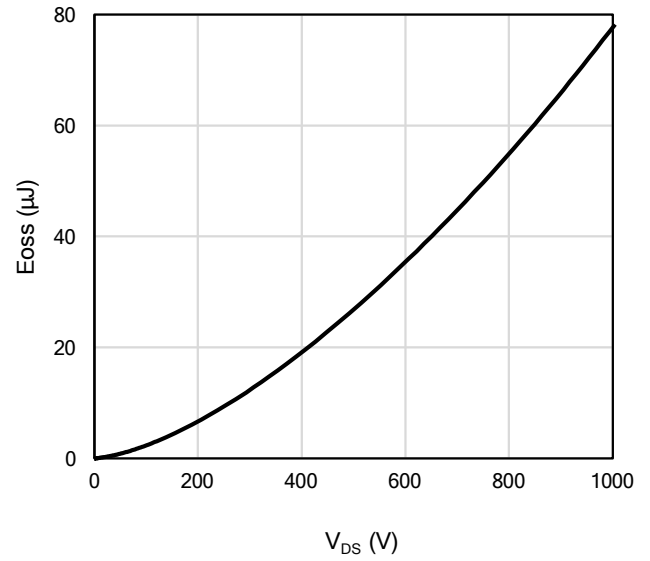


Figure 16: Output Capacitor Stord Energy

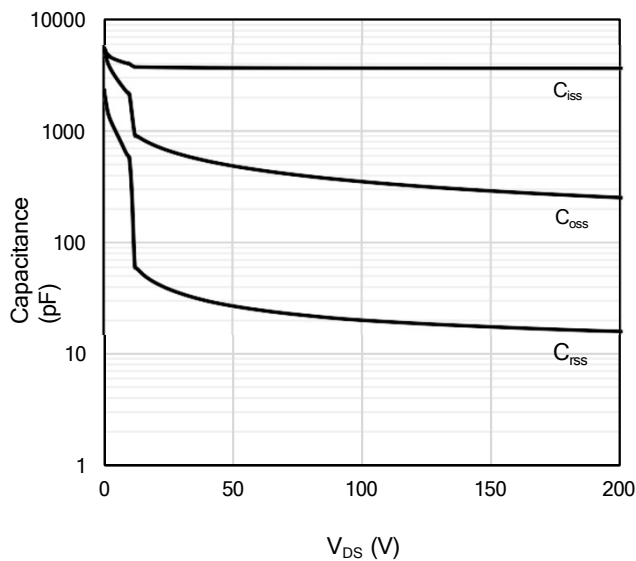


Figure 17: Capacitance Characteristics (0 - 200 V)

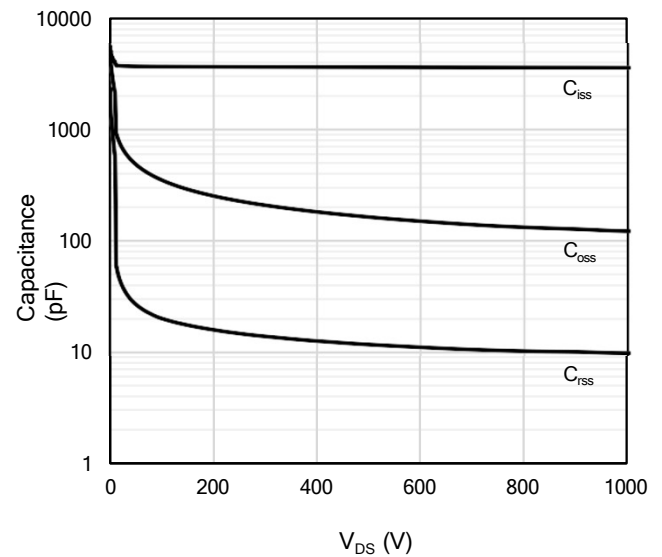


Figure 18: Capacitance Characteristics (0 - 1000 V)

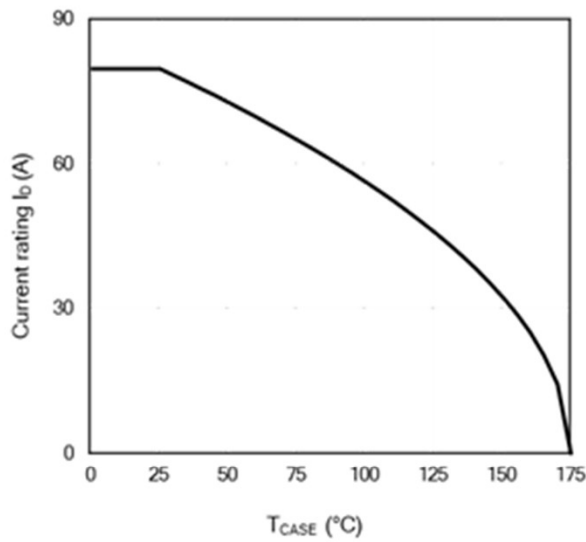


Figure 19: Current De-rating

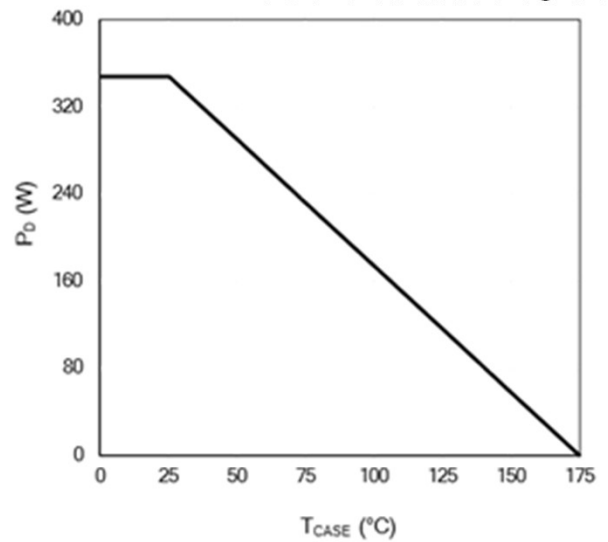


Figure 20: Maximum Power Dissipation Derating vs. Case Temperature

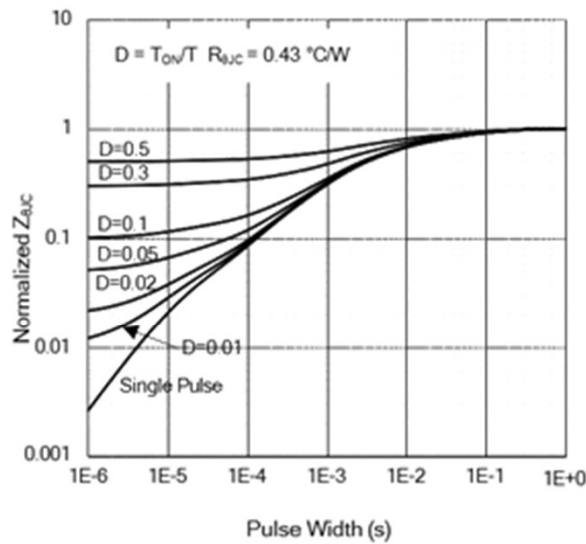


Figure 21: Normalized Maximum Transient Thermal Impedance

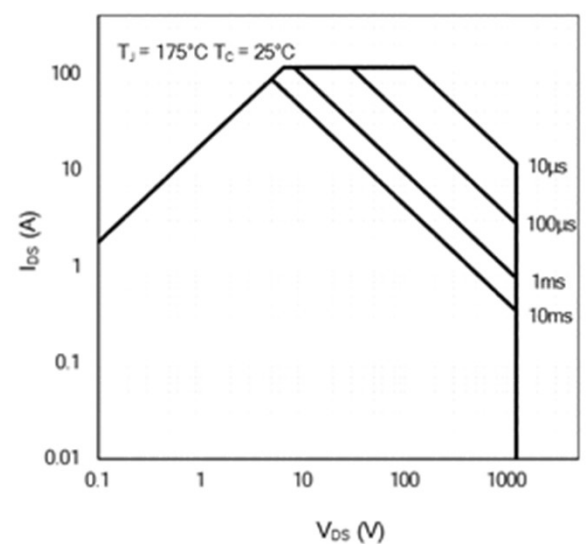


Figure 22: Maximum Forward Biased Safe Operating Area

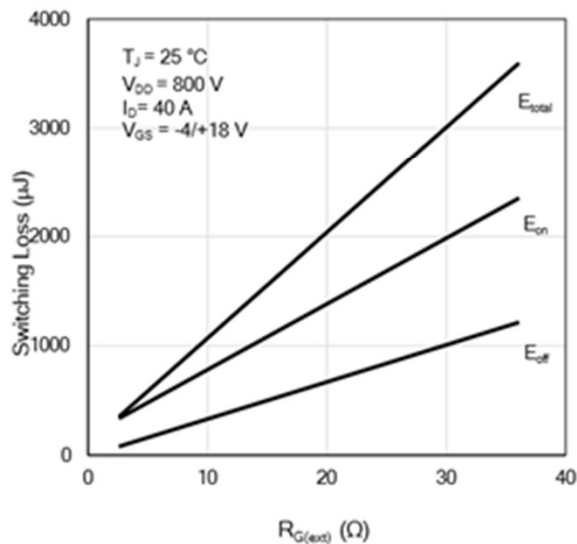


Figure 23: Clamped Inductive Switching Energy vs. $R_{G(ext)}$

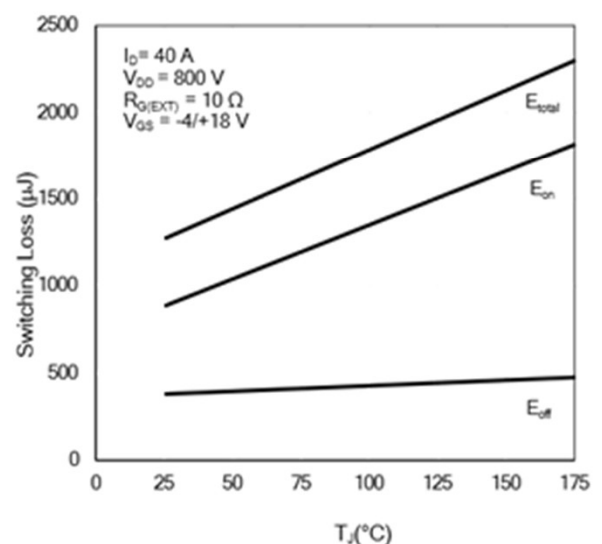


Figure 24: Clamped Inductive Switching Energy vs. T_J

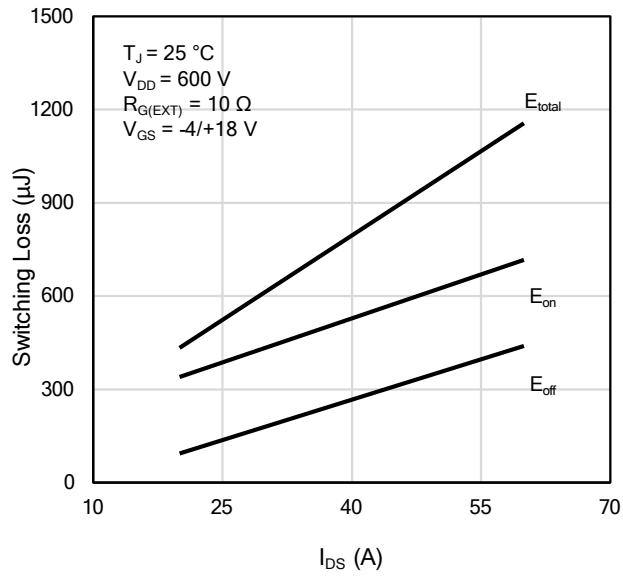


Figure 25: Clamped Inductive Switching Energy vs. Drain Current ($V_{\text{DD}} = 600 \text{ V}$)

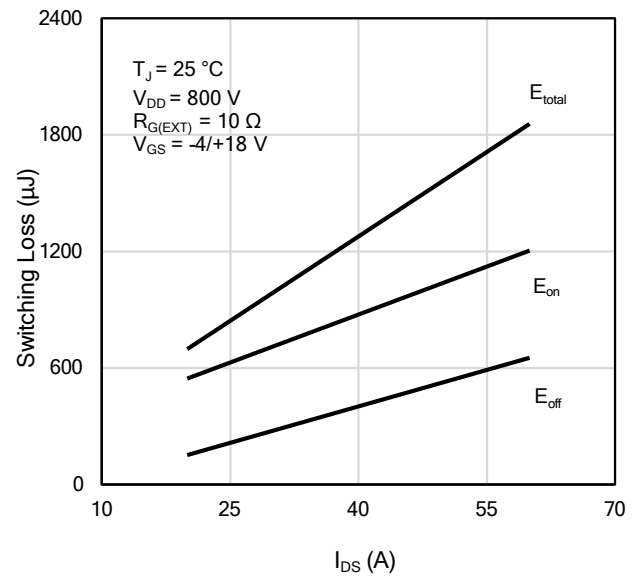


Figure 26: Clamped Inductive Switching Energy vs. Drain Current ($V_{\text{DD}} = 800 \text{ V}$)

Technical drawing of a 10-pin D-subminiature connector, showing front, side, and rear views with dimensions and tolerances.

Front View (Left): Shows the connector body with dimensions E, (12.7), (6.35), E3, E2, (φ3), L2, L1, F, G, e1, e, 4x b, and (8.38). A note indicates "POLISH" for the contact pins.

Side View (Middle): Shows the profile of the connector with dimensions A, A2, W, and A1.

Rear View (Right): Shows the back of the connector with dimensions E1, E4, D2, D1, D3, b5, b1, 3x b3, H, and φ7.18. A note indicates "POLISH" for the contact pins.

Tolerances: The drawing includes tolerance boxes for various dimensions, such as $\pm 0.25(M) B A(M)$ and $\pm 0.64(M) D B(M)$.



Package Outline: TO-247-4L

NOTE :

1. ALL METAL SURFACES: TIN PLATED, EXCEPT AREA OF CUT
2. DIMENSIONING & TOLERANCING CONFIRM TO ASME Y14.5M-1994.
3. ALL DIMENSIONS ARE IN MILLIMETERS.
ANGLES ARE IN DEGREES.

SYMBOL	MILLIMETERS	
	MIN	MAX
A	4.83	5.21
A1	2.29	2.54
A2	1.91	2.16
b'	1.07	1.28
b	1.07	1.33
b1	2.39	2.94
b2	2.39	2.84
b3	1.07	1.60
b4	1.07	1.50
b5	2.39	2.69
b6	2.39	2.64
c'	0.55	0.65
c	0.55	0.68
D	23.30	23.60
D1	16.25	17.65
D2	0.95	1.25
D3	5.55	6.15
E	15.75	16.13
E1	13.10	14.15
E2	3.68	5.10
E3	1.00	1.90
E4	12.38	13.43
E5	1.95	2.35
e	2.54 BSC	
e1	5.08 BSC	
N	4	
L	17.31	17.82
L1	3.97	4.37
L2	2.35	2.65
øP	3.51	3.65
Q	5.49	6.00
S	6.04	6.30
T	17.5° REF.	
W	3.5° REF.	
X	4° REF.	

Marking Information

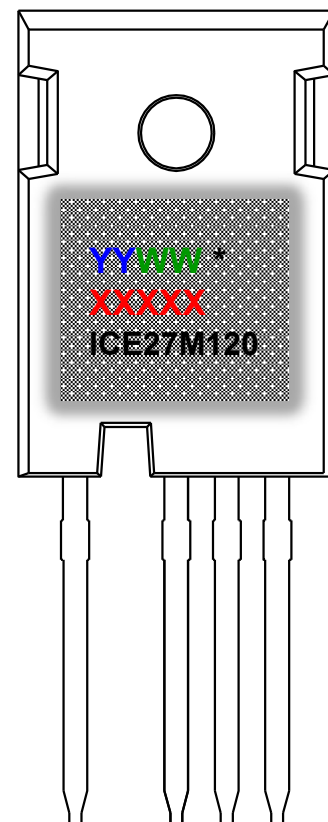
YY = Last two digits of the year

WW = Work week

***** = Site ID

XXXXXX = Lot ID

ICE27M120 = ICE is IceMOS logo and
27M120 is a designated device part
number



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